EXPERT 10.6 HXV

5,300 W Rework station

Rework Station with 5,300 W hybrid under-heating system. The heating area of 450x420 mm^2 is adjustable to PCB size. Automated SMD placement process by Auto Vision Placer (AVP) incl. EASYSOLDER 07 software package and DBL 06 control unit with six high resolution sensors inputs for thermocouples (Type K). This system is particularly suitable for large size PCBs like PCs, Laptops and Server Boards with small up to very big components.

Top Features

Camera-supported rework

Flexibility
Various PCB sizes and shapes as well as components available up to 75 x 75 mm2

Under-heating system
Large PCBs 500 x 500 mm2

Performance
Uniform heat distribution through convection and hybrid technology

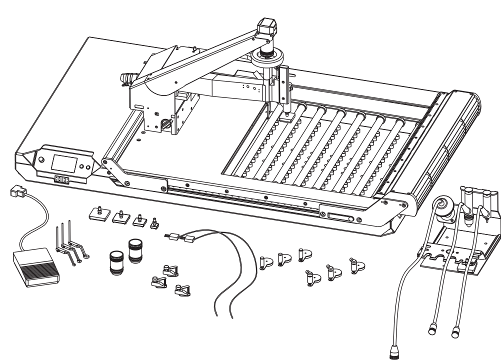
Multifunctionality
One device for all processes, including desoldering, pad cleaning, automatic positioning and soldering

Process control
Automatic profiler for under- and top-heating systems

Software
Simple, intuitive, tablet-compatible

Standard equipment

- Tool set for dispensing, placing, residual solder removal and soldering with magazine
- Set of placement nozzles XL-type (BGA/CSP) 5 mm, 8 mm, 15 mm with O-Ring
- Set of solder nozzles (BGA) 15 mm, 27 mm, 35 mm, 40 mm
- Two camera lenses (BGA und CSP)
- Two thermocouple sensors (type K)
- Six PCB magnet holder 40,5 mm (3x standard, 3x Easy Lock)
- Three PCB clips to install at hand rest
- Foot switch
- Rework ABC and manual
- Intuitive software EASYSOLDER 07 with touch integration



Technical details

Power consumption:	5500 VA	
Power solder pen:	300 W, 35 l/min	
Power under-heating system:	1200 - 5000 W	8 x IR-lamps
Size under-heating system:	450 x 420 mm^2	
Max. PCB size:	480 x 480 mm^2	
Resolution motion system:	0,001 mm	
Placement accuracy:	± 0,015 mm	(Flip Chip)*
	± 0,030 mm	(CSP)
	± 0,040 mm	(BGA)
	± 0,070 mm	(Maxi BGA)*
	± 0,115 mm	(Maxi BGA XL)*

High resolution CMOS-camera:	5 Mio. Pixel USB2	
Camera field of view (FOV):	16 x 22 mm^2	(Flip Chip)*
	32 x 42 mm^2	(CSP)
	42 x 57 mm^2	(BGA)
	71 x 96 mm^2	(Maxi BGA)*
	115 x 160 mm^2	(Maxi BGA XL)*
Mains:	1Phase, 230VAC, Fuse 25A	Connector Type CEE 32A (3 phase)
Pressurized air:	5-8 bar, 100 l/min,	clean, dry air
Dimensions:	1030 x 630 mm^2	

* Optional extras

EXPERT 10.6 HXV: Optional extras

	Article nr.	Name
	SF71.0002	IR temperature sensor für AVP04.1XL
	SF66.0501	Tool Shuttle 40 for AVP 4.1XL
	SF64.0525	Dip Tool 0.08mm with squeegee for tool shuttle 32 / 40
	SF64.0526	Dip Tool 0.15mm with squeegee for tool shuttle 32 / 40
	SF64.0527	Dip Tool 0.22mm with squeegee for tool shuttle 32 / 40
	SF66.0526	Dip Tool 0.15mm with squeegee for tool shuttle 40 only
27mm 23mm 17mm 15mm 12mm 12x18mm 11x14mm	AT10.0100	Chip Frame Set Dip Tool 7 / 32*32mm 7 pcs (11*14,12*18,12,15,17,23,27)
	AT20.0100	Chip Frame Set Dip Tool 7 / 40*40mm 7 pcs (15,17,23,27,31,35,37.5)
	SF64.0520	Print Tool with squeegee for tool shuttle 32 / 40
N_2	DB00.0025	Nitrogen input for DBL 04/05/06 (2.p.r) reduces consumption of N2 for vacuum
Maxi-BGA AVP4	SF66.0110	Lens Maxi BGA for AVP4/4XL, f=16mm, 65*85mm
9 11 13 16	LW40.1096	Soldering nozzle set CSP/QFN 4 for all CSP types, 4 pieces (9, 11, 13, 16)
9 11 13 16	LW40.1104	Soldering nozzle set CSP with vacuum 4 for all CSP types, 4 pieces (9, 11, 13, 16)
	LW40.1099	Solder Nozzle Set BGA 7 7 pieces (15, 23, 27, 31, 35, 37.5, 40)
	SF36.1002	PCB flex support h=40.5 mm for HIF 09, "12 pin"
	SF71.0005	Side Camera (lens 16mm) for ES 05, camera, stand, cable, DVD
	SF71.0008	Lens Side Camera f=25mm

More accessories and consumables at www.martin-smt.de

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